

SAW Filter datasheet

3.0 x 3.0 mm, SMD

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SAW Bandpass Filters | Wireless Communications



Features

Features

- 902.5 MHz center frequency
- Ceramic package for Surface Mounted Technology
- 25 MHz usable Passband
- 50 Ω Single Configuration

Applications

GSM Tx RF SAW Filter

$3.0 \times 3.0 \text{ mm}$



Maximum Ratings

Parameter	Min.	Тур.	Max.	Unit
Storage temperature range (T _{stg})	-40		85	°C
Operating temperature range (T _A)	-30		85	°C
DC voltage (V _{DC})			0	V
Maximum Input Power Handling			10	dBm

Frequency and Electrical Characteristics (Reference temperature @ 25°C)

Parameter	Min.	Typ. ¹	Max.	Unit
Source impedance ² (Single ended)		50		Ω
Load impedance ² (Single ended)		50		Ω
Center frequency (fc)		902.5		MHz
Bandwidth (BW, passband width)	25.00			MHz
Insertion Loss (IL, 890 – 915 MHz)		2.9	3.6	dB
Amplitude ripple (890 – 915 MHz)		0.5	1.6	dB
VSWR (890 – 915 MHz)		1.5	2.3	dB
Absolute Attenuation				
DC to 845.0 MHz	45	51		
From 925.3 to 935.3 MHz	5	21		dB
From 935.3 to 980 MHz	25	28		
From 980 to 1200 MHz	50	54.8		
From 1200 to 3000 MHz	25	28		
Temperature coefficient of frequency		-35		ppm/K

Issue: Rev 4, 9 January 2023

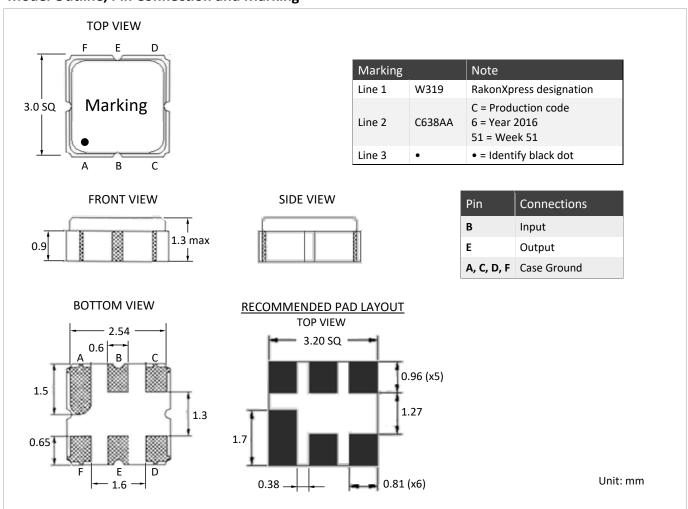
 $^{^{\}rm 1}\,{\rm Typical}$ values are nominal performances at room temperature

 $^{^2}$ No matching network required for operation at 50 $\Omega\,$

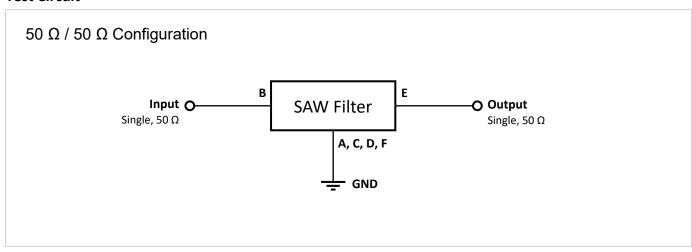




Model Outline, Pin Connection and Marking



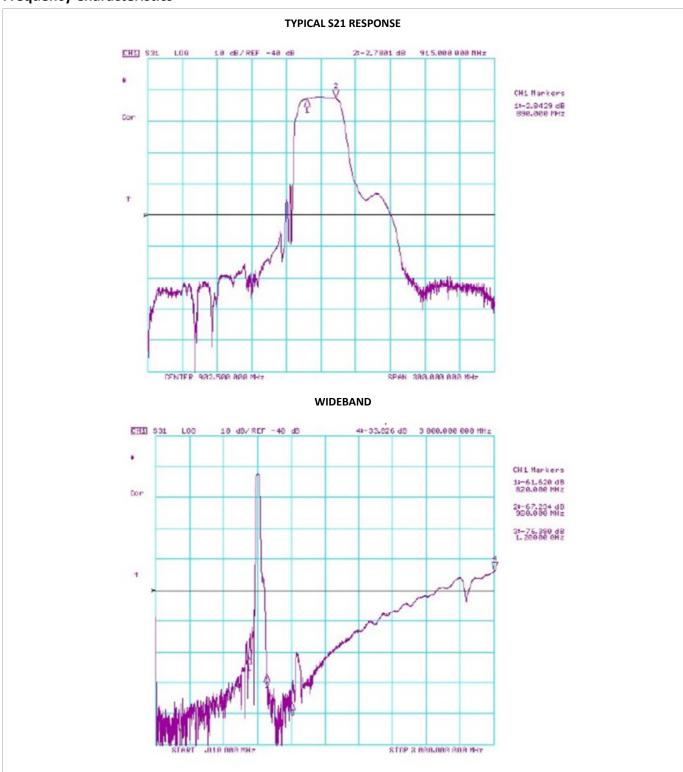
Test Circuit



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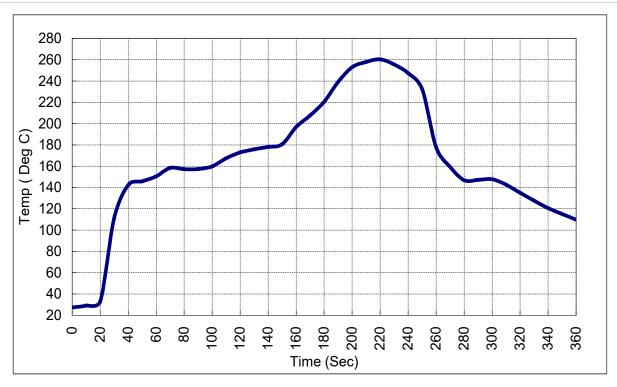
Frequency Characteristics







Recommended Reflow Soldering Profile



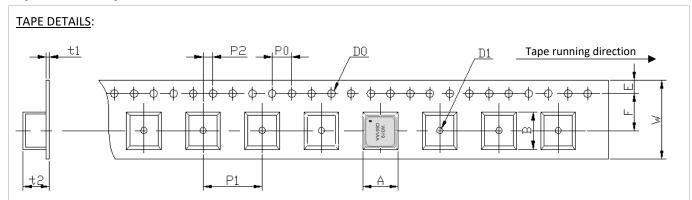
NOTE:

- The components shall remain within the electrical specifications after it soldered on the 1mm thickness PCB board and dipped in the solder at 260 ±5°C during 10 ± 1 seconds.
- The components shall remain within the electrical specifications after it soldered by electric iron, solder at 350 ± 10 °C during 3~4 seconds. Recovery time: 2 ±0.5h.
- Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- Only leads of component may be soldered. Please avoid soldering another part of component.

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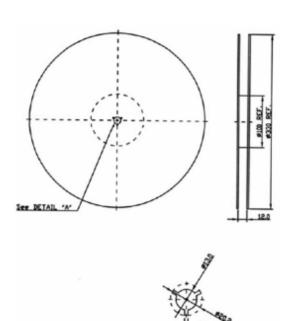


Tape and Reel Specifications



Parameter	Code	Dimension	Tolerance
Height of component hole	Α	3.35 max	
Width of component hole	В	3.35 max	
Diameter of sprocket hole	D ₀	Ф 1.5	± 0.1
Diameter of feed hole	D ₁	Ф 1.5	± 0.25
Pitch of sprocket hole	P ₀	4.0	± 0.2
Length from hole center to component center	P ₁	8.0	± 0.1
Length from Pocket hole center to sprocket hole center	P ₂	2.0	± 0.2
Width of carrier tape	W	12.0	± 0.3
Width of adhesive tape	F	5.5	± 0.3
Gap of hold down tape and carrier tape	E	1.75	± 0.1
Thickness of Ebossed tape sheet	t1	0.31 max	
Thickness of Ebossed tape	t2	1.7 max	

REEL DETAILS:



NOTE:

- Unit: mm
- Standard Packing Quantity (SPQ) is 1000 pieces/ reel

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